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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	512
Number of Gates	-
Number of I/O	193
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5512mv-75fn256i



Product Line	Ordering Part Number	Product Status	Reference PCN
LC51024MV	LC51024MV-52F484C	Active / Orderable	
	LC51024MV-52FN484C		
	LC51024MV-75F484C		
	LC51024MV-75FN484C		
	LC51024MV-75F484I		
	LC51024MV-75FN484I		
	LC51024MV-52F672C		
	LC51024MV-52FN672C		
	LC51024MV-75F672C		
	LC51024MV-75FN672C		
	LC51024MV-75F672I		
	LC51024MV-75FN672I		
LC51024MB	LC51024MB-52F484C	Discontinued	PCN#09-10
	LC51024MB-52FN484C		
	LC51024MB-75F484C		
	LC51024MB-75FN484C		
	LC51024MB-75F484I		
	LC51024MB-75FN484I		
	LC51024MB-52F672C		
	LC51024MB-52FN672C		
	LC51024MB-75F672C		
	LC51024MB-75FN672C		
	LC51024MB-75F672I		
	LC51024MB-75FN672I		
LC51024MC	LC51024MC-52F484C	Discontinued	PCN#09-10
	LC51024MC-52FN484C		
	LC51024MC-75F484C		
	LC51024MC-75FN484C		
	LC51024MC-75F484I		
	LC51024MC-75FN484I		
	LC51024MC-52F672C		
	LC51024MC-52FN672C		
	LC51024MC-75F672C		
	LC51024MC-75FN672C		
	LC51024MC-75F672I		
	LC51024MC-75FN672I		

Cascading For Wide Operation

In several modes it is possible to cascade adjacent MFBs to support wider operation. Table 2 details the different cascading options. There are chains of MFBs in each device which determine those MFBs that are adjacent for the purposes of cascading. Table 3 indicates these chains. The ispXPLD 5000MX design tools automatically cascade blocks if required by a particular design.

Table 2. Cascading Modes For Wide Support

Mode	Cascading Function
Logic	Input Width. Allows two MFBs to act as a 136-input block.
	Arithmetic. Allow the carry chain to pass between two MFBs.
FIFO	Memory Width Expansion. Allows MFBs to be cascaded for greater width support.
CAM	Memory Width Expansion. Allows up to four MFBs to be cascaded for greater width support.

Table 3. MFB Cascade Chain

Device	MFBs in Cascade Chain
ispXPLD 5256MX	A → B → C → D
	H → G → F → E
ispXPLD 5512MX	A → B → C → D → E → F → G → H
	P → O → N → M → L → K → J → I
ispXPLD 5768MX	D → C → B → A → X → W → V → U → T → S → R → Q
	E → F → G → H → I → J → K → L → M → N → O → P
ispXPLD 51024MX	H → G → F → E → D → C → B → A → AF → AE → AD → AC → AB → AA → Z → Y
	I → J → K → L → M → N → O → P → Q → R → S → T → U → V → W → X

SuperWIDE Logic Mode

In logic mode, each MFB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and four control product terms. The MFB has 68 inputs from the Global Routing Pool, which are available in both true and complement form for every product term. It is also possible to cascade adjacent MFBs to create a block with 136 inputs. The four control product terms are used for shared reset, clock, clock enable, and output enable functions. Figure 3 shows the overall structure of the MFB in logic mode while Figure 4 provides a more detailed view from the perspective of a macrocell slice.

Single-Port SRAM Mode

In Single-Port SRAM Mode the multi-function array is configured as a single-port SRAM. In this mode one port accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 11 shows the block diagram of the single-port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Reset is asynchronous. All signals share a common clock, clock enable, and reset. Table 7 shows the possible sources for the clock, clock enable and reset signals.

Figure 11. Single-Port SRAM Block Diagram

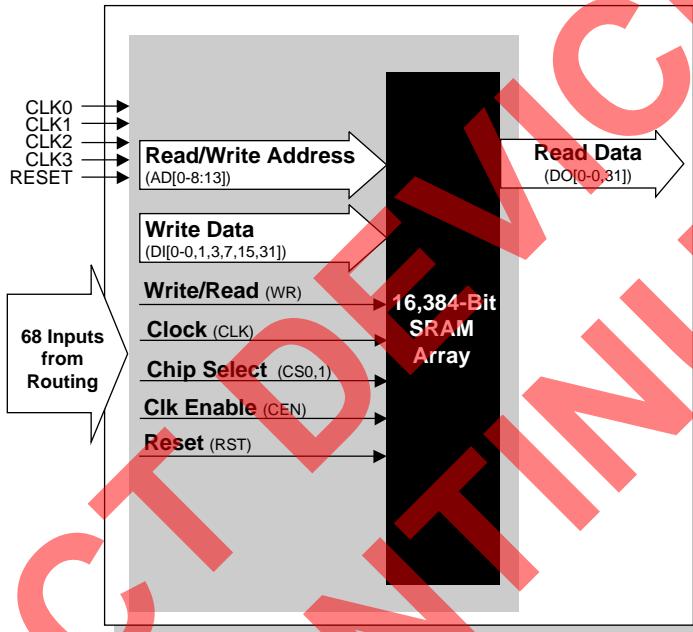


Table 7. Register Clock, Clock Enable, and Reset in Single-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/Write, and Chip Select	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	CEN or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

Absolute Maximum Ratings^{1, 2, 3}

	ispXPLD 5000MC 1.8V	ispXPLD 5000MB/V 2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied ^{4, 5}	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to ($V_{IHMAX} + 2$) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with $V_{IN} > 3.6V$ is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage for 1.8V Devices (ispXPLD 5000MC)	1.65	1.95	V
	Supply Voltage for 2.5V Devices (ispXPLD 5000MB)	2.3	2.7	V
	Supply Voltage for 3.3V Devices (ispXPLD 5000MV)	3	3.6	V
V_{CCP}	PLL Block Supply Voltage for PLL 1.8V Devices	1.65	1.95	V
	PLL Block Supply Voltage for PLL 2.5V Devices	2.3	2.7	V
	PLL Block Supply Voltage for PLL 3.3V Devices	3	3.6	V
T_J	Junction Temperature (Commercial Operation)	0	90	C
	Junction Temperature (Industrial Operation)	-40	105	C

E²CMOS Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle ¹	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics^{1, 2, 3, 4}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	0 $\leq V_{IN} \leq$ 3.0V	—	+/-50	+/-800	μ A

1. Insensitive to sequence of V_{CC} and V_{CCO} when $V_{CCO} \leq 1.0V$. For $V_{CCO} > 1.0V$, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO} , provided $(V_{IN} - V_{CCO}) \geq 3.6V$.
2. 0 $\leq V_{CC} \leq V_{CC}$ (MAX), 0 $\leq V_{CCO} \leq V_{CCO}$ (MAX)
3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} . Device defaults to pull-up until non-volatile cells are active.
4. LVTTL, LVCMOS only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}^1	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCO} - 0.2V)$	—	—	10	μA
		$(V_{CCO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	μA
I_{IH}^4	Input High Leakage Current	$3.6V < V_{IN} \leq 5.5V$ and $3.0V \leq V_{CCO} \leq 3.6V$	—	—	3	mA
I_{PU}^3	I/O Active Pullup Current	$0 \leq V_{IN} \leq 0.7 V_{CCO}$	-30	—	-150	μA
I_{PD}	I/O Active Pulldown Current	$V_{IL} (\text{MAX}) \leq V_{IN} \leq V_{IH} (\text{MAX})$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (\text{MAX})$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (\text{MAX})$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (\text{MAX})$	—	—	150	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (\text{MAX})$	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	μA
C1	I/O Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	8	—	pf
C2	Clock Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	8	—	pf
C3	Global Input Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. $T_A = 25^\circ C$, $f=1.0\text{MHz}$
3. I_{PU} on JTAG pins has a maximum of $-175\mu A$ for 5512MX devices.
4. 5V tolerant inputs and I/Os should be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.									
t _{FIFOWES}	Write-Enable setup before Write Clock	—	2.33	—	2.33	—	2.91	—	2.91	—	3.03	—	ns
t _{FIFOWEH}	Write-Enable hold after Write Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns
t _{FIFORES}	Read-Enable setup before Read Clock	—	2.69	—	2.35	—	2.79	—	2.38	—	4.14	—	ns
t _{FIFOREH}	Read-Enable hold after Read Clock	—	-3.17	—	-3.17	—	-2.53	—	-2.53	—	-2.44	—	ns
t _{FIFORSTO}	Reset to Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
t _{FIFORSTR}	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
t _{FIFORSTPW}	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
t _{FIFORCLKO}	Read Clock to FIFO Out Delay	—	—	3.73	—	3.73	—	4.66	—	4.66	—	4.84	ns
CAM – Update Mode													
t _{CAMMSS}	Memory Select Setup before CLK	—	1.40	—	0.70	—	1.50	—	1.40	—	1.44	—	ns
t _{CAMMSH}	Memory Select Hold after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMENMSKS}	Enable Mask Register Setup Time before CLK	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMENMSKH}	Enable Mask Register Setup Time after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMADDS}	Address Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMADDH}	Address Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMDATAS}	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
t _{CAMDATAH}	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMDCTS}	“Don’t Care” Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMDCH}	“Don’t Care” Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMRWS}	R/W Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMRWH}	R/W Enable Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMCES}	Clock Enable Setup Time before Clock	—	1.55	—	1.55	—	1.94	—	1.94	—	2.02	—	ns
t _{CAMCEH}	Clock Enable Hold Time after Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.									
t_{PDPRWH}	R/W Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPDATAS}$	Data Setup before Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{PDPDATAH}$	Data Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPRCLKO}$	Read Clock to Output Delay	—	—	5.08	—	5.02	—	5.66	—	5.45	—	8.54	ns
$t_{PDPCLKSKEW}$	Opposite Clock Cycle Delay	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	—	ns
$t_{PDPRSTO}$	Reset to RAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{PDPRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{PDPRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
Dual Port RAM													
t_{DPMSAS}	Memory Select A Setup Before R/W A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSAH}	Memory Select Hold time after R/W A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPCEAS}	Clock Enable A Setup before Clock A Time	—	3.72	—	3.72	—	3.72	—	3.72	—	4.84	—	ns
t_{DPCEAH}	Clock Enable A Hold time after Clock A Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
$t_{DPADDAS}$	Address A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPADDAH}$	Address A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPRWAS}	R/W A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPRWAH}	R/W A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{DPDATAAS}$	Write Data A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPDATAAH}$	Write Data A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPMSBS}	Memory Select B Setup Before R/W B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSBH}	Memory Select Hold time after R/W B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.									
t_{DPCEBS}	Clock Enable B Setup before Clock B Time	—	2.33	—	2.33	—	2.33	—	2.33	—	3.03	—	ns
t_{DPCEBH}	Clock Enable Hold B after Clock B Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
$t_{DPADDBS}$	Address B Setup before Clock B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPADDBH}$	Address B Hold time after Clock B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPRWBS}	R/W B Setup before Clock B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPRWBH}	R/W B Hold time after Clock B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{DPDATABS}$	Write Data B Setup before Clock B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPDATABH}$	Write Data B Hold after Clock B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{DPRCLKAO}$	Read Clock A to Output Delay	—	—	5.97	—	5.92	—	5.86	—	5.65	—	9.86	ns
$t_{DPRCLKBO}$	Read Clock B to Output Delay	—	—	5.16	—	5.16	—	5.16	—	5.16	—	6.71	ns
$t_{DPCLKSKEW}$	Opposite Clock Cycle Delay	—	1.40	—	1.40	—	1.40	—	1.40	—	1.83	—	ns
t_{DPRSTO}	Reset to RAM Output Delay	—	—	3.30	—	3.30	—	3.30	—	3.30	—	4.29	ns
t_{DPRSTR}	Reset Recovery Time	—	1.20	—	1.20	—	1.20	—	1.20	—	1.56	—	ns
$t_{DPRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.14	—	0.14	—	0.19	—	ns

Timing v.1.8

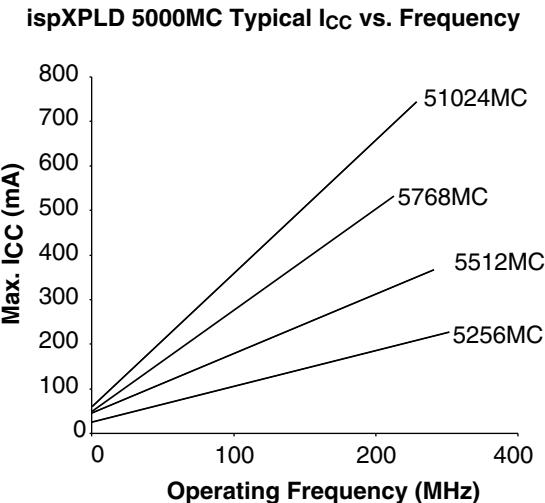
1. The PT-delay to clock of RAM/FIFO/CAM should be t_{BCLK} instead of t_{PTCLK} .
2. The PT-delay to set/reset of RAM/FIFO/CAM should be t_{BSR} instead of t_{PTSR} .

ispXPLD 5000MX Family Timing Adders (Continued)

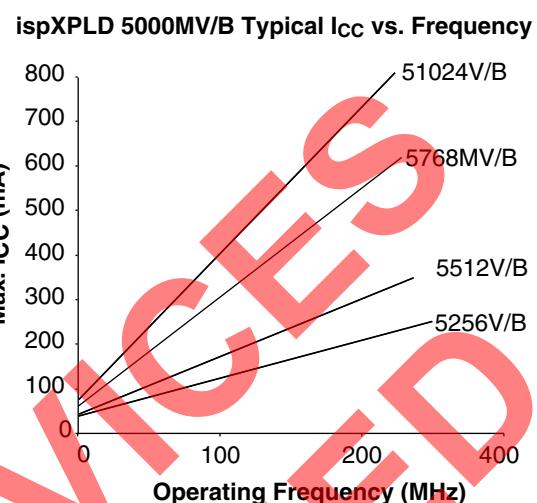
Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.									
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_out	Using HSTL 2.5V, Class IV	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
PCI_out	Using PCI Standard	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns

Timing v.1.8

Power Consumption



Note: The device is configured with maximum number of 16-bit counters, no PLL, typical current at 1.8V, 25°C.



Note: The device is configured with maximum number of 16-bit counters, no PLL, typical current at 3.3V (MV) or 2.5V (MB), 25°C.

Power Estimation Coefficients

Device	K0	K1	K2	K3	K4	K5	K6	K7	DC	
	ispXPLD 5000MC	ispXPLD 5000MV/B							ispXPLD 5000MC	ispXPLD 5000MV/B
ispXPLD 5256	2.2	8.4	7	12	100	0.1379	0.0433	6.476	16	24
ispXPLD 5512	2.2	8.4	9.4	18	151	0.1379	0.0433	6.476	17	25
ispXPLD 5768	2.2	8.4	10.2	21	170	0.1379	0.0433	6.476	27	36
ispXPLD 51024	2.2	8.4	13	27.6	200	0.1379	0.0433	6.476	35	43

Note: For further information about the use of these coefficients, refer to TN1031 – [Power Estimation in ispXPLD 5000MX Devices](#).

Memory Coefficients

Device	K8	K9	K10	K11
ispXPLD 5256	0.004719	0.0924	4.4	2.9
ispXPLD 5512	0.004719	0.0924	4.4	2.9
ispXPLD 5768	0.004719	0.0924	4.4	2.9
ispXPLD 51024	0.004719	0.0924	4.4	2.9

- K0 = Current per MFB input ($\mu\text{A}/\text{MHz}$)
- K1 = Current per Product Term ($\mu\text{A}/\text{MHz}$)
- K2 = Current per GRP from MFB ($\mu\text{A}/\text{MHz}$)
- K3 = Current per GRP from I/O ($\mu\text{A}/\text{MHz}$)
- K4 = Global clock tree current ($\mu\text{A}/\text{MHz}$)
- K5 = PLL digital (mA/MHz)
- K6 = PLL analog (mA/MHz)
- K7 = PLL analog baseline (mA)
- DC = Baseline current at 0MHz (mA)
- K8 = CAM frequency component (mA/MHz)
- K9 = CAM DC component (mA)
- K10 = Current per row decoder ($\mu\text{A}/\text{MHz}$)
- K11 = Current per column driver ($\mu\text{A}/\text{MHz}$)

ispXPLD 5000MX Power Supply and NC Connections¹

**SELECT DEVICES
DISCONTINUED**

Signals	208 PQFP ⁴	256 fpBGA ^{3,5}	484 fpBGA, 5 ³	672 fpBGA ^{3,5}
VCC	10, 49, 76, 114, 153, 180	D4, D13, F6, F11, L6, L11, N4, N13	A17, A6, AA2, AA21, AB17, AB6, B2, B21, D19, D4, F1, F22, G10, G11, G12, G13, K16, K7, L16, L7, M16, M7, T10, T11, T12, T13, T14, T9, U1, U22, W19, W4	AA21, AA6, F21, F6, G20, G7, J13, J14, K13, K14, L13, L14, M13, M14, N10, N11, N12, N15, N16, N17, N18, N9, P10, P11, P12, P15, P16, P17, P18, P9, R13, R14, T13, T14, U13, U14, V13, V14, Y20, Y7
VCCO0	5, 17, 189, 204	A1, F7, G6	B9, C3, G8, G9, H7, J2, J7, P4	H10, H11, H8, H9, J8, J9, K8, L8, M8, N8
VCCO1	42, 57, 72	K6, L7, T1	AA9, R7, T3, T8, Y3	P8, R8, T8, U8, V8, V9, W10, W11, W8, W9
VCCO2	85, 100, 107, 121	K11, L10, T16	AA14, R16, T15, T20, Y20	P19, R19, T19, U19, V18, V19, W12, W13, W14, W15, W16, W17, W18, W19
VCCO3	146, 161, 176	A16, F10, G11	B14, C20, G14, G15, H16, J16, J21, P19	H12, H13, H14, H15, H16, H17, H18, H19, J18, J19, K19, L19, M19, N19
VCCP	136	J16	M22	N25
VCCJ	27	J1	M1	N4
GND	15, 29, 44, 81, 119, 148, 185, 7, 19, 191, 205, 40, 56, 70, 87, 101, 109, 123, 144, 160, 174	K1, C3, C14, E5, E12, G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10, M5, M12, P3	N1, A1, A2, A21, A22, AA1, AA22, AB1, AB22, B1, B22, C15, C8, D11, D12, E18, E5, F17, F6, G16, G7, H10, H11, H12, H13, H14, H15, H20, H3, H8, H9, J10, J11, J12, J13, J14, J15, J8, J9, K10, K11, K12, K13, K14, K15, K8, K9, L10, L11, L12, L13, L14, L15, L19, L4, L8, L9, M10, M11, M12, M13, M14, M19, M4, M9, N10, N11, N12, N13, N14, N9, P10, P11, P12, P13, P14, P9, R10, R11, R12, R13, R14, R15, R8, R9, T16, T7, W11, W12, Y15, Y8	A11, A16, A2, A25, AE1, AE2, AE25, AE26, AF11, AF16, AF2, AF25, B1, B2, B25, B26, J10, J11, J12, J15, J16, J17, K10, K11, K12, K15, K16, K17, K18, K9, L1, L10, L11, L12, L15, L16, L17, L18, L26, L9, M10, M11, M12, M15, M16, M17, M18, M9, N13, N14, P13, P14, R10, R11, R12, R15, R16, R17, R18, R9, T1, T10, T11, T12, T15, T16, T17, T18, T26, T9, U10, U11, U12, U15, U16, U17, U18, U9, V10, V11, V12, V15, V16, V17
GNDP	134	K16	N22	P26
NC ²	—	5256MX: A2, A11, A12, A15, B2, B12, B15, B16, C4, C12, C15, C16, D1, D11, D14, D15, D16, E1, E4, E10, E11, E13, E14, F4, F5, F12, F13, L1, L4, M3, M7, M13, N2, N6, P1, P2, P5, P6, P13, P14, P15, P16, R1, R2, R4, R5, R6, R16, T2, T3, T4, T5, T6 5512MX/5768MX: L1	5512MX: P1, AA19, AB2, AB21, J17, J6, K1, K17, K18, K19, K2, K20, K21, K22, K3, K4, K5, K6, L1, L17, L18, L2, L20, L21, L22, L3, L5, L6, M15, M17, M18, M2, M20, M21, M3, M5, M6, M8, N15, N17, N18, N19, N2, N20, N21, N3, N4, N5, N6, N8, P15, P17, P18, P2, P21, P22, P5, P6, P8, U17, U6, V18, V5, W6 5768MX/51024MX: None	A12, A13, A14, A15, AA10, AA11, AA12, AA13, AA14, AA15, AA16, AA17, AA7, AB10, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AC10, AC11, AC12, AC13, AC14, AC15, AC16, AC17, AD11, AD12, AD13, AD14, AD15, AD16, AE11, AE12, AE13, AE14, AE15, AE16, AF12, AF13, AF14, AF15, B11, B12, B13, B14, B15, B16, C11, C12, C13, C14, C15, C16, C3, D10, D11, D12, D13, D14, D15, D16, D17, E10, E11, E12, E13, E14, E15, E16, E17, E6, E7, E8, F10, F11, F12, F13, F14, F15, F16, F17, G10, G11, G12, G13, G14, G15, G16, G17, Y10, Y11, Y12, Y13, Y14, Y15, Y16, Y17

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.
3. Balls for GND, V_{CC} and V_{CCOx} are connected within the substrate to their respective common signals. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
4. Pin orientation follows the conventional counter-clockwise order from pin 1 marking of the topside view.
5. Internal GNDs and I/O GNDs (Bank 0 - Bank 3) are connected inside package. V_{CCO} balls connect to four power planes within the package, one each for V_{CCOx}.

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
3	51N	F2	E1	F1	F3	B8
3	51P	F0	E0	F0	F1	C8
0	52N	G30	G31	H31	G31	B7
0	52P	G28	G30	H30	G29	A7
-	-	GND	-	-	-	NC
0	53N	G26	G29	H29	G27	D7
0	53P	G24	G28	H28	G25	C7
0	54N	G22	G27	H27	G23	B6
-	-	VCCO0	-	-	-	VCCO0
0	54P	G21	G26	H26	-	E7
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)
0	55N	G20	G25	H25	-	E6
0	55P	G18	G24	H24	G19	A6
0	56N	G16/VREF0	G3	H3	G17	A5
0	56P	G14	G2	H2	G15	A4
0	57N	G12	G23	H23	G13	B5
0	57P	G10	G22	H22	G11	A3
0	58N	G8	G21	H21	G9	B4
0	58P	G6	G20	H20	G7	B3
0	59N	G5	G19	H19	-	C5
0	59P	G4	G18	H18	-	C6
0	60N	G2	G1	H1	G3	D5
0	60P	G0	G0	H0	G1	D6
-	-	VCCO0	-	-	-	VCCO0
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
—	GCLK0N	GCLK1	—	—	—	28	J2	P7
—	—	GND	—	—	—	29	GND	GND
—	—	TDI	—	—	—	30	H6	R1
—	—	TMS	—	—	—	31	H4	R2
—	—	TCK	—	—	—	32	J6	T1
—	—	TDO	—	—	—	33	K2	V1
1	0P	A0/DATA0	B0	D0	A1	34	K3	W1
1	0N	A2/DATA1	B1	D1	A3	35	J3	Y1
1	1P	A4/DATA2	B2	D2	A5	36	J5	P3
1	1N	A6/DATA3	B3	D3	A7	37	J4	R3
1	2P	A8/DATA4	B4	D4	A9	38	L2	T2
1	2N	A10/DATA5	B5	D5	A11	39	M1	U2
—	—	GND (Bank 1)	—	—	—	40	GND (Bank 1)	GND (Bank 1)
1	3P	A12/DATA6	B6	D6	A13	41	K4	V2
—	—	V _{CCO1}	—	—	—	42	V _{CCO1}	V _{CCO1}
1	3N	A14/DATA7	B7	D7	A15	43	L3	W2
—	—	GND	—	—	—	44	GND	GND
1	4P	A16/INITB	B8	D8	A17	45	K5	R4
1	4N	A18/CSB	B9	D9	A19	46	L5	T4
1	5P	A20/READ	B10	D10	A21	47	N1	R6
1	5N	A22/CCLK	B11	D11	A23	48	M2	R5
1	6P	A24	—	—	A25	—	—	U3
—	—	VCC	—	—	—	49	VCC	VCC
1	6N	A26	—	—	A27	—	P1 ¹	V3
1	7P	A28	—	—	A29	—	M3	Y2
1	7N	A30	—	—	A31	—	L4	W3
1	8P	B0	A0	—	B1	—	N2	U5
1	8N	B2	A2	—	B3	—	P2	T5
—	—	GND (Bank 1)	—	—	—	—	GND (Bank 1)	GND (Bank 1)
1	9P	B4	A4	—	—	—	R1	U4
—	—	V _{CCO1}	—	—	—	—	V _{CCO1}	V _{CCO1}
1	9N	B5	A6	—	—	—	R2	V4
1	10P	B6	A8	—	B7	—	T2	AA3
1	10N	B8	A10	—	B9	—	T3	AB3
1	—	B10	A12	—	B11	—	—	Y4
—	—	DONE	—	—	—	50	M4	AA4
1	11P	B14	B12	D12	B15	51	N3	AB4
1	11N	B16	B13	D13	B17	52	P4	AB5
1	12P	B18	B14	D14	B19	53	N5	T6
1	12N	B20	B15	D15	B21	54	M6	U7
—	—	PROGRAMB	—	—	—	55	R3	W5
1	—	B22	A14	—	B23	—	P5	U8
—	—	GND (Bank 1)	—	—	—	56	GND (Bank 1)	GND (Bank 1)

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	GCLK3N	GCLK2	-	-	-	H15	P16
-	-	VCCP	-	-	-	See Power Supply and NC Connections Table	
-	GCLK3P	GCLK3	-	-	-	H16	N16
3	61N	J0	L31	J31	-	H14	J22
3	61P	J2	L30	J30	J3	G16	H22
3	62N	J4	L29	J29	J5	—	N19
3	62P	J6	L28	J28	J7	—	P15
3	63N	J8	L27	J27	J9	—	P21
3	63P	J10	L26	J26	J11	—	N15
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	64N	J12	L25	J25	J13	—	M15
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	64P	J14	L24	J24	J15	—	N20
-	-	GND	-	-	-	GND	GND
3	65N	J16	L23	J23	J17	—	P22
3	65P	J18	L22	J22	J19	—	N21
3	66N	J20	L21	J21	J21	—	N17
3	66P	J22	L20	J20	J23	—	M20
3	67N	J24	L19	J19	J25	—	P17
-	-	VCC	-	-	-	VCC	VCC
3	67P	J26	L18	J18	J27	—	P18
3	68N	J28	L17	J17	J29	—	M21
3	68P	J30	L16	J16	J31	—	M17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	69N	L0	L15	J15	-	—	L20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	69P	L2	L14	J14	L3	—	N18
3	70N	L4	L13	J13	L5	—	L21
3	70P	L6	L12	J12	L7	—	M18
3	71N	L8	L11	J11	L9	—	L22
3	71P	L10	L10	J10	L11	—	L17
3	72N	L12	L9	J9	L13	—	K22
3	72P	L14	L8	J8	L15	—	L18
3	73N	L16	L7	J7	L17	—	K21
3	73P	L18	L6	J6	L19	—	K18
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	74N	L20	L5	J5	L21	—	K20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	74P	L22	L4	J4	L23	—	K17
3	75N	L24	L3	J3	L25	—	K19
3	75P	L26	L2	J2	L27	—	J17
3	76N	L28	L1	J1	L29	G15	E22

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	175N	AC22	AC27	AE27	AC23	K6	J5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	175P	AC20	AC26	AE26	AC21	K3	J4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	176N	AC18	AC25	AE25	AC19	K5	K7
0	176P	AC16	AC24	AE24	AC17	K2	L7
0	177N	AC14	AC23	AE23	AC15	L5	J3
0	177P	AC12	AC22	AE22	AC13	K1	J2
0	178N	AC10	AC21	AE21	AC11	L6	K6
0	178P	AC8	AC20	AE20	AC9	L1	L6
0	179N	AC6	AC19	AE19	AC7	M5	K5
0	179P	AC4	AC18	AE18	AC5	L2	K4
0	180N	AC2	AC17	AE17	AC3	N5	K3
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	180P	AC0	AC16	AE16	AC1	L3	K2
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	181N	AE30	AC15	AE15	AE31	M6	K1
0	181P	AE28	AC14	AE14	AE29	M2	L2
0	182N	AE26	AC13	AE13	AE27	P5	L5
-	-	VCC	-	-	-	VCC	VCC
0	182P	AE24	AC12	AE12	AE25	P6	L4
0	183N	AE22	AC11	AE11	AE23	M3	L3
0	183P	AE20	AC10	AE10	AE21	N6	M3
0	184N	AE18	AC9	AE9	AE19	N2	M7
0	184P	AE16	AC8	AE8	AE17	P1	N7
-	-	GND	-	-	-	GND	GND
0	185N	AE14	AC7	AE7	AE15	N3	M5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	185P	AE12	AC6	AE6	AE13	M8	M4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	186N	AE10	AC5	AE5	AE11	N8	M6
0	186P	AE8	AC4	AE4	AE9	P2	N6
0	187N	AE6	AC3	AE3	AE7	P8	M2
0	187P	AE4	AC2	AE2	AE5	N4	M1
0	188N	AE2	AC1	AE1	AE3	H1	N1
0	188P	AE0	AC0	AE0	AE1	J1	N2
-	GCLK0P	GCLK0	-	-	-	N7	N5
-	-	VCCJ	-	-	-	See Power Supply and NC Connections Table	
-	GCLK0N	GCLK1	-	-	-	P7	N3
-	-	GND	-	-	-	GND	GND
-	-	TDI	-	-	-	R1	P4
-	-	TMS	-	-	-	R2	P5

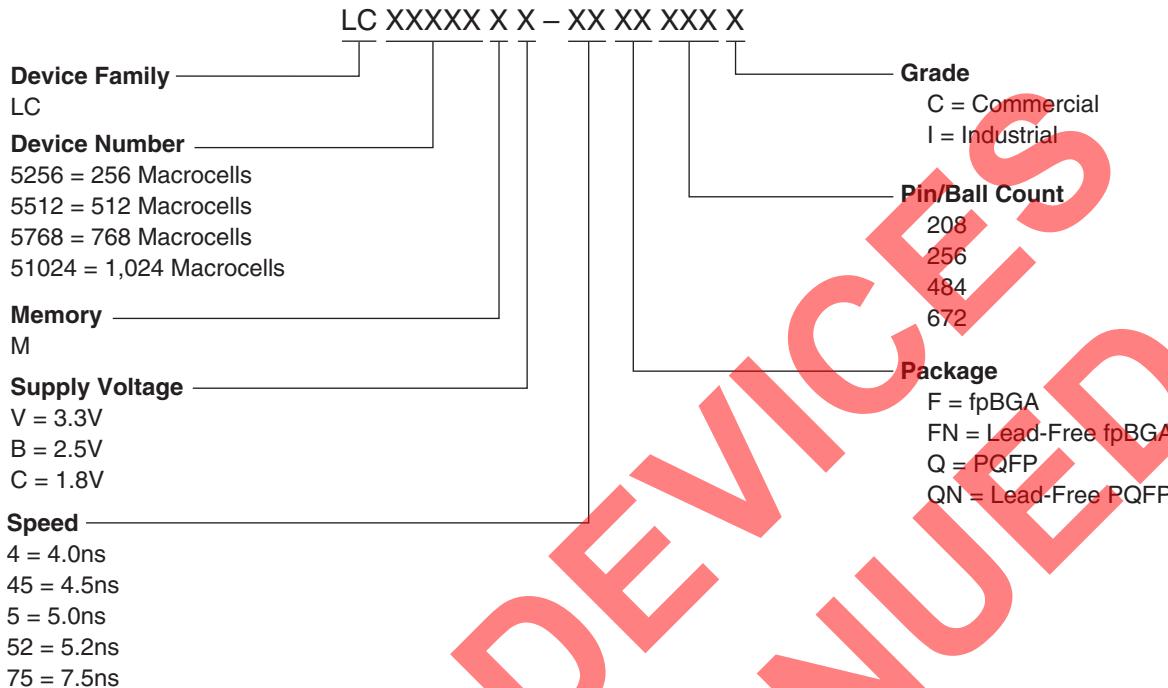
ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	110N	U4	X25	V25	U5	H21	J21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	110P	U6	X24	V24	U7	G21	H21
-	-	GND	-	-	-	GND	GND
3	111N	U8	X23	V23	U9	D22	G25
3	111P	U10	X22	V22	U11	D21	G24
3	112N	U12	X21	V21	U13	J20	G23
3	112P	U14/CLK_OUT1	X20	V20	U15	J19	G22
3	113N	U16	V31	-	U17	E20	J20
-	-	VCC	-	-	-	VCC	VCC
3	113P	U18	V30	U30	U19	F20	H20
3	114N	U20	V29	U28	U21	H17	G26
3	114P	U22	V28	U26	U23	H18	F25
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	115N	U24	V27	-	U25	J18	F24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	115P	U26	V26	-	U27	H19	F23
3	116N	U28	V25	-	U29	G20	G21
3	116P	U30	V24	-	U31	G19	F22
-	-	GND	-	-	-	GND	GND
3	117N	V0	V23	-	V1	C22	F26
-	-	VCC	-	-	-	VCC	VCC
3	117P	V2	V22	-	V3	C21	E26
3	118N	V4	V21	-	V5	D20	E25
3	118P	V6	V20	-	V7	C19	E24
3	119N	V8	V19	-	V9	F19	E23
3	119P	V10	V18	-	V11	E19	E22
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	120N	V12	V17	-	V13	G18	D26
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	120P	V14	V16	-	V15	F18	D25
3	121N	V16	V15	-	V17	B20	D24
3	121P	V18	V14	-	V19	B19	D23
3	122N	V20	V13	-	V21	A20	C26
3	122P	V22	V12	-	V23	A19	C25
3	123N	V24	X19	V19	V25	D18	G19
3	123P	V26	X18	V18	V27	C18	F19
3	124N	V28	X17	V17	V29	G17	G18
3	124P	V30	X16	V16	V31	F16	F18
3	125N	W0	X31	V31	W1	E17	F20
3	125P	W2	X30	V30	W3	D17	E20
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

**SELECT DEVICES
DISCONTINUED**

Part Number Description



Ordering Information

Note: For voltage families offered in industrial temperature grades and for all but the slowest commercial speed grade, the speed grades on these devices are dual marked. For example, the commercial speed grade -45XXXXC is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade is marked as commercial grade only. In addition, the fastest commercial speed grade (-5) for the LC5768MB/MV devices, at Lattice's discretion, will utilize either a commercial grade only single-mark or a dual-mark format in conjunction with the slower industrial speed grade (-75).

Conventional Packaging

ispXPLD 5000MC (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t _{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-4F256C	256	1.8	4.0	fpBGA	256	141	C
	LC5256MC-5F256C	256	1.8	5.0	fpBGA	256	141	C
	LC5256MC-75F256C	256	1.8	7.5	fpBGA	256	141	C
LC5512MC	LC5512MC-45Q208C	512	1.8	4.5	PQFP	208	149	C
	LC5512MC-75Q208C	512	1.8	7.5	PQFP	208	149	C
	LC5512MC-45F256C	512	1.8	4.5	fpBGA	256	193	C
	LC5512MC-75F256C	512	1.8	7.5	fpBGA	256	193	C
	LC5512MC-45F484C	512	1.8	4.5	fpBGA	484	253	C
	LC5512MC-75F484C	512	1.8	7.5	fpBGA	484	253	C

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
December 2003	07	Added ispXPLD 5768MX information (supply current, timings, power consumption, power estimation coefficients, memory coefficients, logic signal connections, ordering part numbers).
		Updated ispXPLD 5000MX timing numbers (version v.1.7).
		Added lead-free package designator.
		Removed ispXPLD 5000MC industrial temperature grade ordering part numbers.
January 2004	08	Lead-free package release for the ispXPLD 5000MC and 5000MV devices.
		Timing model parameter tCOi correction - Maximum specification instead of Minimum (no changes in the timing numbers).
March 2004	08.1	Updated the MFB Cascade Chain table for the ispXPLD 5256MX device.
May 2004	09	Updated the ispXPLD 5000MX timing numbers (version v.1.8)
		ispXPLD 5256MC, 5512MC and 51024MC industrial temperature grade devices release
		Updated typical supply current data and condition.
		ispXPLD 5256MX 256-fpBGA logic signal connection tables: Removed internal signal description for ball H5 and G14.
August 2004	10	Added footnote "1, page 49. These inputs should not toggle during power up for proper power-up configuration." to CCLK and READ.
		Added ispXPLD 5768MC Industrial grade OPNs (Conventional and Lead-Free).
October 2004	10.1	Figure 19, LVPECL Driver with Three Resistor Pack has been updated (ispXPLD LVPECL Buffer changed to ispXPLD Emulated LVPECL Buffer)
November 2004	11	Added ispXPLD 5000MB (2.5V) Lead-Free Ordering Part Numbers.
December 2004	11.1	Pin name RESETB has been updated to RESET.
March 2005	12	208-PQFP Lead-free package release for the ispXPLD 5512MV/B/C devices.
April 2005	12.1	Page 23, clarification of footnote regarding IDK specification.
March 2006	12.2	Signal description for RESET has been updated.
April 2009	12.3	Ordering Information section has been updated to describe alternate LC5768MB/MV top side marking format.
February 2010	12.4	References to "system gates" changed to "functional gates."